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Contributions Welcome
Readers are encouraged to submit news items concerning the Society and its members. Please send your ideas/articles directly to either the Editor or appropriate Associate Editor. All contact information is listed on page 2. Whenever possible, email is the preferred form of submittal.

Newsletter Deadlines

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The 1994 GaAs IC Symposium will feature integrated circuit technologies in GaAs, InP, and other compound semiconductors and will be held at the Wyndham Franklin Plaza Hotel, Philadelphia, PA, October 16-19, 1994.

In its 16th year, the GaAs IC Symposium continues its tradition of service to the compound semiconductor IC technical community. As the premier forum in the field, the Symposium has matured with the industry, emphasizing the manufacturing and applications areas in recent years. The main objective of the Symposium has been to maintain thorough representation of all aspects of the compound semiconductor IC community: materials, devices, techniques, circuit design, testing, packaging and applications. In addition, the Symposium features several very popular and highly interactive sessions. The 1993 Symposium's measure of success was apparent as paper submissions were at a record high and attendance was up 35%. Another first for 1993 was that 40% of the attendees classified themselves as GaAs IC customers.

What's driving this broad based surge in GaAs IC interest? There are several factors. Digital systems that require speed and precision are finding GaAs (continued on page 3)

Your Comments Solicited
This is the first issue of the new EDS Newsletter. Your comments and suggestions are most welcome. Please write directly to the Editor of the Newsletter at the address given on page 2.
Message from the Outgoing President

As outgoing president of the Society, I wanted to give members an update on the status of the Society and some of the new initiatives.

One of the most visible initiatives is this newsletter. The need for the newsletter became clear during our recent attempt to reach out to our chapters and become more global. It was obvious that we were very disconnected from our chapters and that our chapters were very disconnected from each other. These problems were much greater internationally than in the US. The newsletter is an attempt to get back in touch with our members and chapters and to allow our chapters to communicate with their members and other chapters. This increased interaction will be particularly important as we grow internationally by increasing our presence and offering new members more for their membership.

Relative to the above, international growth is the single biggest priority for the Society. Our field is already international and growing more so. Presently EDS has 33% of its members outside the US with this number growing at a rate of 5-8% per year, offsetting a decline in membership in the US. In spite of this level of membership, we are presently not a major force in either Europe or Asia. On the other hand, we are the only society in the field of electron devices that has a reasonable chance of becoming a truly global society. By being truly global, we will be able to serve all of our membership better by providing for interchange among the entire worldwide technical community.

Last year the Society made two fact-finding trips, one to Asia in May and one to Europe in September. The goals of both trips were twofold. The first was to improve our membership service by increasing our involvement with technical meetings and getting feedback on any issues with our journals or awards. The second was to increase our membership and the number of our chapters. In Europe, for example, we have eight chapters compared to 18 for the Microwave Theory and Techniques Society (MTTS) which is about the same size as EDS. Both trips concentrated on visiting our chapters, since they are our base of operations in both regions. The reaction to our visits was overwhelmingly positive and there was a genuine appreciation of the fact that we took the effort to make the trip.

The salient points of the feedback we received were:

(continued on page 5)
GaAs coupled with its compatibility with silicon circuits has shifted the use of the technology. Not only is GaAs successfully deployed in supercomputers, but in microprocessor based systems as well. In the analog market, the interest in compound semiconductor ICs can be summed up in the word wireless. Last year, the number of cellular and pager subscribers increased by over 5 million (source: Yankee Group). This growth is expected to continue. To this is added 1.5-1.8 million new wireless data LANs and WANs in the US for 1994 (source: Taylor & Associates). The wireless industry is more than just healthy. Some market analysts predict a 3-fold growth for the LANs and WANs after 1995 and the opportunity above 800 MHz is attracting semiconductor suppliers to GaAs ICs. World market analysts predict a 3-fold growth for the LANs and WANs after 1995 and the opportunity above 800 MHz is attracting semiconductor ICs to new wireless digital applications. The composition of this forum depends on the responses we receive. For questions or comments on the Vendor Product Forum, please contact Wes Mickanin at TriQuint Semiconductor, E-MAIL: wsm@tqs.com or TEL # (503) 671-0767, ext. 248.

If the technical intensity has worn down, then the Symposium's social events or the affordable city of Philadelphia should revive the most exhausted spirit. With as many as four days of presentations, the Executive Committee tries to balance the program with informal social functions. Starting with an opening reception Sunday evening at the Wyndham and continuing Tuesday evening at the Franklin Institute Science Museum, the symposium organizers have sought to facilitate information exchange outside the traditional technical format. Even with last year's symposium topping 500 participants, most found the symposium highly interactive as well as informative. If you've been to the GaAs IC Symposium in the past, you know what we mean.

1994 GaAs IC Symposium

(continued from page 1)

ICs as a cost-effective solution, particularly in clocking functions. The affordability of GaAs coupled with its compatibility with silicon circuits has shifted the use of the technology. Not only is GaAs successfully deployed in supercomputers, but in microprocessor based systems as well. In the analog market, the interest in compound semiconductor ICs can be summed up in the word wireless. Last year, the number of cellular and pager subscribers increased by over 5 million (source: Yankee Group). This growth is expected to continue. To this is added 1.5-1.8 million new wireless data LANs and WANs in the US for 1994 (source: Taylor & Associates). The wireless industry is more than just healthy. Some market analysts predict a 3-fold growth for the LANs and WANs after 1995 and the opportunity above 800 MHz is attracting semiconductor ICs to new wireless digital applications. The composition of this forum depends on the responses we receive. For questions or comments on the Vendor Product Forum, please contact Wes Mickanin at TriQuint Semiconductor, E-MAIL: wsm@tqs.com or TEL # (503) 671-0767, ext. 248.

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1994 Bipolar/BiCMOS Circuits and Technology Meeting (BCTM)

The 1994 BCTM will be held at the Minneapolis Marriott Hotel on October 10-11, 1994. This focused meeting will concentrate on developments in wide bandwidth analog and mixed-signal ICs and high-performance digital BiCMOS. Supporting subjects such as device modeling, device physics, and CAD will also be well represented. About 350 engineers from the US, the Pacific Rim and Europe are expected to attend. Preliminary indications are that we will have attendance and papers from a record number of foreign countries. The size and organization of the meeting fosters vigorous exchange of ideas in an

(continued on page 6)
W. DEXTER JOHNSTON, Jr. (President) — (BS Physics 1961, Yale College; Ph.D Physics 1966, MIT). He joined the AT&T Bell Laboratories, Holmdel, NJ in 1966, and carried out research on lasers, nonlinear optics and ferroelectric materials, photovoltaic devices, and compound semiconductors. From 1980 through 1992 he led the development of vapor phase epitaxial growth for the manufacture of lasers used in AT&T fiber optic communications systems. He is currently Technical Manager, Semiconductor Laser R & D at AT&T Bell Laboratories, Murray Hill, NJ and is responsible for expediting advanced photonic devices from concept to prototype. He has authored over 100 papers, a book on solar cell technology, and holds 23 US patents. He was an Associate Editor of the EDS Electron Devices Letters from 1983 to 1989, and was EDS Publications Chairman from 1989 to 1991. He is a Fellow of the IEEE.

LOUIS C. PARRILLO (Vice President) — (BSEE 1964, Univ. of Connecticut; MSEE 1967 and Ph.D 1972, Princeton University). In 1972, he joined the AT&T Bell Laboratories, Murray Hill, NJ and worked on semiconductor technology, leading to the development of twin-tub CMOS. In 1984 he joined Motorola in Austin, TX, and in 1988 became Vice President of the Technical Staff and Director of the Advanced Products Research and Development Laboratory, managing over 400 research and support staff responsible for the development and transfer of manufacturing of new CMOS and BiCMOS technologies. In 1992, he and Richard Payne received the EDS J.J. Ebers Award for their contributions to CMOS and Bipolar IC technology. He was General Chairman of the 1990 IEDM. He has published over 40 conference and journal papers, and has 28 issued or pending patents. He is a Fellow of the IEEE.

LUCIAN A. KASPRZAK (Treasurer) — (BS Physics 1965, Stevens Institute of Technology; MS Physics 1970, Syracuse University; Ph.D Materials 1972, Stevens Institute of Technology). He joined IBM in 1965, working on failure analysis, MOS and bipolar process development, and VLSI reliability. In 1992, he joined the faculty of Franciscan University, Steubenville, OH. He received IBM awards for the discovery of the hot electron effect (1974) and development of a reliable low barrier Schottky diode (1980). He is Chair of the EDS Device Reliability Committee, EDS representative to the Int. Reliability Physics Symposium and was on the Advisory Board for the Circuits and Devices Magazine. He has been General Chairman and Technical Program Chairman for IRPS. He has 26 publications and 3 patents. Since 1989 has been the Director of the Center for Quantized Electronic Structures, an NSF Science and Technology Center. His present research interests include optical properties of semiconductors, optoelectronic ICs, and low-dimensional quantum structures. He was Chairman of the Department of ECE 1982-84 and Associate Dean for Research Development of the College of Engineering 1984-1986. He received an honorary doctorate from Linkoping University, Sweden, in 1993. He has over 250 publications and 5 patents. He is a Fellow of the IEEE and the American Physical Society.

JAMES L. MERZ (Secretary) — (BS Physics 1959, Notre Dame University; MA Applied Physics 1961 and Ph.D Applied Physics 1967, Harvard University). He joined the AT&T Bell Laboratories in 1966, in 1978 became Professor of EE at UC Santa Barbara, Santa Barbara, CA and since 1989 has been the Director of the Center for Quantized Electronic Structures, an NSF Science and Technology Center. His present research interests include optical properties of semiconductors, optoelectronic ICs, and low-dimensional quantum structures. He was Chairman of the Department of ECE 1982-84 and Associate Dean for Research Development of the College of Engineering 1984-1986. He received an honorary doctorate from Linkoping University, Sweden, in 1993. He has over 250 publications and 5 patents. He is a Fellow of the IEEE and the American Physical Society.

— Lewis M. Terman, IBM Research Center, Yorktown Heights, NY

EDS Members Elected to the IEEE Grade of Fellow
effective January 1, 1994

Yalcin Ayasli
Yiu-chung Cheng
Aristos Christou
Ching-Te K. Chuang
Mihai D. Draganescu
Lawrence N. Dworsky
Aicha Elshabini-Riad
Jeffrey I. Frey

Ronald J. Gutmann
Evelyn L. Hu
Genda J. Hu
Charles C. Huang
Huey liang Hwang
James Cheng M. Hwang
Walton J. Kitchen, Jr.
Herbert A. Leupold

Mark S. Lundstrom
Noel C. MacDonald
Akira Masaki
Toshiaki Masuhashi
Hans W. Poetzl
Karl H. Schoenbach
James P. Spratt
Johannes M.C. Stork

Robert G. Swartz
Richard J. Temkin
Sandip Tiwari
Rory L. Van Tuyl
Wen I. Wang
Robert J. Weber
Horst R. Wittmann
Gerard T. Wrixon
Message from the Outgoing President
(continued from page 2)

1. The need for better communication with the Society and with other chapters; hence the newsletter.
2. The need for support for chapter meetings such as distinguished lecturers and video tapes of short courses and plenary talks.
3. Continued interaction with Society officers and Society sponsorship of a yearly regional chapter chairs' meeting.
4. The need for expanded financial support for chapter activities, support in sponsoring regional chapter technical meetings, and communications for chapter meetings.
5. The need to increase the number of IEEE awards, Fellow elections, and paper acceptances for Europe and Asia.
6. The need for special support for Eastern Europe such as subsidized memberships and filling gaps in technical libraries.

In the case of the latter, presently the Society is pursuing initiatives in both these areas. The first is being done jointly with MTTS where each society will sponsor a 50% reduction in IEEE dues for 12 members in each of five countries. We are also working with the Commission on European Activities Board to give back issues of journals to libraries in Eastern European countries. The latter is as a result of feedback that missing back issues and gaps were a major problem in their libraries.

Other outcomes of the trip are initiatives to form new chapters in Europe and Asia. Presently, discussions are under way with Austria, Benelux, Egypt, Finland, France, Central/South Italy, Poland, South Africa, Spain, Sweden, and Turkey. A new chapter was formed in Hong Kong as a result of the Asia trip. We will also be increasing our involvement in a number of technical meetings, most notably the ESSDERC meeting which is Europe's premier yearly meeting on electron devices. In addition, we are expanding our support activities for chapters whereby we offer approximately US$50 a year for chapter projects. This program is administered by our Sections/Chapters Committee. His committee evaluates proposals that are submitted by Chapters on a yearly zero-based budget process.

Our present plans are to have another round of these visits in 1994 to further extend our initiatives and to jump-start a chapter chairs' meeting in Region 8. One of the keys to these trips will be to foster new chapter formation and begin to form alliances with regional technical societies.

In other Society news, we now have a revised Society Constitution and By-Laws which updates many of our procedures. Most notably, the number of elected AdCom Members-at-Large has been increased from 18 to 22, with the requirement of at least two members from each of IEEE Regions 8 and 10 (Europe/Mid East/Africa and Asia, respectively). We also have a Society logo as a result of Lew Termann's (our Senior Past President) efforts in this area. The Society continues to grow in its meeting support, now sponsoring or cosponsoring 32 meetings and cooperating with 45 more. Our ten journals are healthy and our newest one, the Journal of Microelectromechanical Systems is entering its second full year of operation. Society membership stayed about constant or slightly down at ~11,000 members, not a bad feat in the poor economic times of the last few years. Finally, the Society remains very strong financially with a growing surplus resulting from strong meeting revenues and break-even performance on journals.

Overall, the Society is in excellent condition and is on a track to grow in membership, technical services and become a truly global society. I am personally very pleased to have been part of the Society growth and will continue to work for the Society as past president.

— Michael S. Adler,
General Electric Co., 1 River Road,
Scheneectady, NY 12301

EDS Distinguished Lecturer Program

EDS is seeking qualified candidates for its Distinguished Lecturer Program. It is designed to present leading-edge and exciting technical research to the EDS chapters and members as well as to facilitate communications among members, chapters, EDS and IEEE. Anyone who routinely gives talks at major technical meetings should consider participating in this program. If you are interested, please contact the EDS Educational Activities Chair, Jerry M. Woodall; his contact information is listed on page 2.

Chapter Subsidies for 1995

Requests for subsidies from Chapters are due on August 1, 1994. Last year the EDS AdCom awarded funding for 1994 to 13 Chapters, with amounts ranging between US$350 and US$1,000. Letters to Chapter Chairs were sent in May, 1994 notifying them of the current funding cycle. A list of guidelines was enclosed with each letter. In general, activities which are considered fundable include, but not limited to: membership promotion; travel allowances for invited speakers to Chapter events; and support for student activities at local institutions. Letters requesting subsidies should be sent to the EDS Executive Office at the address given on page 2. Final decisions on awards will be made by the EDS Sections/Chapters Committee by early October.

IEEE Electron Devices Society 1994 J.J. Ebers Award Nominations

The IEEE Electron Devices Society invites the submission of nominations for the 1994 J.J. Ebers Award. This award is presented annually by EDS to honor an individual(s) who has made either a single or a series of contributions of recognized scientific, economic, or social significance to the broad field of electron devices. The recipient(s) will receive a certificate and a check for $2,000, presented at the International Electron Devices Meeting (IEDM).

Nomination forms can be obtained from the EDS Executive Office. The deadline for the submission of nominations for the 1994 award is July 15, 1994. Completed nomination forms should be sent to the Executive Office at the address given on page 2.
BCTM (continued from page 3)

atmosphere of participation.

Minneapolis and St. Paul are the core of a metropolitan area of 2 million, with all the big-city attractions of night life, museums, a widely-acclaimed orchestra, professional sports, and the “Mall of America,” acclaimed by its developers to be the world’s largest shopping mall. Early October is a pleasant season of the year with warm days, cool nights, and fall color.

While the final program has not yet been set, it is expected that the following topics will be well-represented:

- Submicron BiCMOS technology
- Ultra-fast bipolar devices, including SiGe and HBts
- Mixed-signal telecommunication and wireless chips
- Gbit/sec bipolar and BiCMOS logic techniques

The 1994 BCTM will feature two evening panel sessions. The first of these will take up “SiGe — What For?” in which the merits of this exciting technology for various real-world applications will be discussed. Touted by some as a competitor for GaAs in the GHz and Gbit/sec area, SiGe devices may re-shape the competitive forces in a number of industries if claimed advantages of cost and performance can be realized in products. This panel session will be organized by David Hareme (IBM) and Alan Solheim (BNR). The second panel session, organized by Tom Fletcher of Intel, will take up “Low Power Design Techniques.” This is quite timely considering the widespread expectations that the next few years will see the emergence of “battery powered everything.” The methods used to achieve acceptable power consumption will be quite diverse. Not only must favorable logic forms such as static CMOS be used, but selected digital and analog blocks need to be turned off when unused, and the logic clocks will be only selectively activated. How is this selection of circuit blocks to be done? By a master controller? By “messages” or “thresholds” inherent in the signals used ...? Can the power-up and power-down be done “glitchlessly”? This should be plenty of fuel for lively exchanges.

A popular feature of BCTM is the presentation of double-length “tutorial” talks on state-of-the-art subjects. Among the commitments received are a talk on “BiCMOS Technology for Analog Integrated Circuits” by Sone and Yotsuyanagi of NEC, Japan; and a tutorial on “Chip-Level Interconnection Issues” by J. L. Prince of the University of Arizona, Tucson, AZ. There will be 3 or 4 more invited talks on other topics. In addition to the conference digest of extended papers, a special issue of the J. Solid-State Circuits entitled “High-Speed IC Design” will feature selected papers from the conference.

If you would like to be placed on the mailing list for the Advance Program, contact Jan Jopke at TEL # (612) 934-5082 or FAX # (612) 934-6741. The Program Committee Chairman is Prof. C. R. Selvakumar of the University of Waterloo, TEL # (519) 885-1211, ext. 3978 and the Vice Chairman is Krishna Shenai of the University of Wisconsin - Madison, TEL # (608) 265-3806.

Report on ESSDERC

One of the results of the Electron Devices Society visit to Europe (IEEE Region 8) was a decision to increase our participation with the ESSDERC meeting. We are currently having discussions on publishing key papers from the conference in our Transactions as well as having an EDS representative on the steering committee. In keeping with the spirit of this increased cooperation, we are including the following information in our newsletter.

GENERAL SCOPE OF THE CONFERENCE

ESSDERC’94 will be the 24th in the series of well-established annual meetings devoted to the physics, technology, characterization and modeling of solid state devices. The conference will be held in the Edinburgh Conference Centre at Heriot-Watt University and delegates will be able to reserve, through The Institute of Physics, residential accommodation in single-study bedrooms on the University campus. Edinburgh also has a number of excellent hotels. The dates for the conference are Sept. 11-15, 1994.

SCIENTIFIC PROGRAM

The program will consist of oral presentations of contributed papers and invited papers grouped in sessions dealing with the four main themes of the conference. The invited papers will be given by international experts in currently important theme topics, and will include the following speakers and topic areas: Mr. Doug Dunn, Chief Executive Officer, Philips Semiconductor International; The Importance of European Silicon VLSI; Prof. Henry Baltes, ETH Zurich: Micrometers Integrated into VLSI; Dr. Conor Rafferty, AT&T Bell Laboratories: Process Modeling of Silicon VLSI Technology; Dr. Peter Baltus, Philips Research Laboratories: High Frequency Communication Integrated Circuits; and Dr. Robert Walker, GEC-Marconi: Microwave-Modulated Optical Waveguides. The main conference themes are: Silicon VLSI Devices and Technology; Silicon Devices and Materials; Silicon Modeling; Compound Semiconductor Devices and Technologies.

LOCATION

The city lies at the heart of the Scottish Microelectronics Industry. The so-called “Silicon-Glen” boasts the largest wafer fabrication capacity in Europe. This is augmented by close links with a number of highly rated university research laboratories and substantial systems design and manufacturing industry.

SOCIAL EVENTS

An extensive social program is planned taking advantage of the numerous places of interest in the Edinburgh area. This will comprise an afternoon devoted to tours of these many attractions and a program for accompanying spouses. All delegates are invited to a Welcome Reception at The Conference Centre on the evening of Sunday, Sept. 11, when they will also be able to register for the conference. On Tuesday, Sept. 13, all delegates and accompanying persons are invited to attend a Civic Reception at The National Museum of Scotland. The Conference Dinner will be held on the evening of Wednesday, Sept. 14, at Hopetoun House, one of Scotland’s finest stately homes.

FURTHER INFORMATION

Further information on all aspects of the conference can be obtained by contacting: The Meetings and Conferences Department, The Institute of Physics, 47 Belgrave Square, London SW1X 8QX, UK; Tel: +44 71 235 611; Fax: +44 71 259 6002; E-mail: IOPCONF@ULCC.AC.UK; Registered Charity Number 293851. The Institute of Physics is a member of IAPCO (International Association of Professional Congress Organizers).

— Michael S. Adler,
EDS Jr. Past President
Chapter Reports

San Diego MTT/AP/ED Joint Chapter
The San Diego, CA Joint Chapter usually holds six to seven meetings each year. These meetings consist of a luncheon followed by one hour lecture; four having been held since September 1993. The first, in September 1993, featured Prof. Lawrence Milstein from University of California, San Diego, CA who delivered an insightful introduction into the burgeoning field of spread spectrum communication. In October 1993, Mr. Jonathan King of Qualcomm Inc. presented a discussion of direct digital synthesis and its application to the rf/microwave engineering. In November 1993, Prof. David Rutledge of the California Institute of Technology, Pasadena, CA explained the utility of a microwave grid placing package in the design of amplifiers and oscillators that his research group has developed. Recently, in January 1994, Art Oliner, Prof. Emeritus, from Polytechnic University in Brooklyn, NY lectured to a feisty crowd on the subject of surface waves and leaky modes in MMICs. In addition, the San Diego Joint Chapter will be the co-host, with the Los Angeles MTT Chapter, of the 1994 IEEE International Microwave Symposium, to be held in the San Diego Convention Center from May 23-27, 1994. It is anticipated to be a great success, as several members of the local chapter have committed themselves to long hours of preparation for the event.

Central Texas EDS Chapter
The Central Texas Chapter of EDS was formally approved in November 1993. The co-organizers were Charles Yarling and John Lowell who are also serving as interim officers until formal elections are held. They feel that the Austin/San Antonio, TX area is ideal for this chapter, drawing interest from the University of Texas at Austin as well as many Semiconductor firms (Motorola, Sony, AMD, Cypress, and Sematech). They anticipate that the chapter will grow to support, co-sponsor, or initiate workshops and seminars in addition to the many other functions such as SEMICON Southwest that meets in Austin, TX. There are also many opportunities for joint work with the local LEOS and Computer Society Chapters. The organizers wish to thank all those who lent their support to this chapter, and they are looking forward to their inaugural year.

Phoenix Waves and Devices Joint Chapter
The Waves and Devices Chapter of the IEEE Phoenix, AZ Section provides local representation for members of six IEEE societies. In addition to EDS, the chapter represents MTT-S, AP-S, EOC-S, UFFC-S and EMCS. The chapter is very active, holding one or two technical meetings per month; seventeen held last year. Two of these talks were by EDS speakers: Brian Skromme (3/11/93) and Dieter Schroder (12/2/93). The chapter is planning a workshop for the fall of 1994.

Spokane Computers/Electronics Joint Chapter
Three meetings are held annually. Their next meeting will be in March 1994 with the title: “Interfacing into Internets.” In May 1994, they will co-sponsor, together with Instrument Society of America, the Inland Empire Electrotechnology ’94 Conference at Spokane, WA.

Region 8
United Kingdom & Republic of Ireland MTT/ED/AP Joint Chapter:
The British and Irish interests of the EDS are served by the United Kingdom and Republic of Ireland (UKRI) MTT/ED/AP Joint Chapter. Other chapters incorporated in the UKRI Section include Aerospace and Electronic Systems, Circuits and Systems, Communications, Computer, Control Systems, Electromagnetic Compatibility, Magnetics, Professional Communications, Signal Processing and Power Electronics. The UKRI Section has about 4000 members. The UKRI MTT/ED/AP Joint Chapter
is managed by a 14 member AdCom, this meets four times each year and represents the interests of the joint parent Societies IEEE membership. Liaison with the national professional bodies is an important function. It has in place a self-accountancy structure and bylaws. The chapter membership as of Sept. 1993, totals 542, subdivided as approximately 275, 188, and 223 for the MTT, ED and AP Societies, respectively (some members belonging to more than one Society).

Briefly, the chapter activities, since 1991, have comprised about ten events each calendar year. An evening lecture series of about 6-8 events, in general spread over venues at London, Leeds, Belfast and Dublin, has formed the core of the program. Other activities, such as self-financing colloquia, workshops and one-day technical meetings, have also been included, when practical. Additional features have been co-operative sponsorship of educational courses and other European chapter events, and membership promotions. All events are publicized in advance in the Region 8 news. In general, meetings attendance has been in the 13 to 60 range. Low meeting attendance, aggravated by the current economic climate and the many wide ranging activities sponsored by the national professional bodies, presents one of the main concerns for the chapter. Financially, the UKRI Section rebate, funding from the parent Societies and support from UKRI universities (e.g. Leeds, London, Belfast, Dublin) have been essential for establishing the chapter and funding the core program.

In 1993, the chapter program consisted of a six lecture series, co-sponsorship of the short course on “Compound Semiconductor Modeling” organized by Leeds University, technical program co-operation for the European chapter workshop on “CAE, Modeling & Measurement Verification,” in co-operation with Microwaves 1994 (M’94), the technical program being organized by the UKRI chapter. Please contact Prof. J. A. C. Stewart, Technical Program Committee Chairman, The Queen’s University of Belfast for more information. Note: The first Workshop was held May 24, 1993 at MIOP’93 Sendelfingen Germany, with the technical program organized by the German chapter in co-operation with the UKRI, French and Italian chapters. Oct. 24: The Wembley Conference Center, Wembley. The 2nd European Chapter Workshop on “CAE, Modeling and Measurement Verification,” in co-operation with Microwaves 1994 (M’94), the technical program being organized by the UKRI chapter. Please contact Prof. J. A. C. Stewart, Technical Program Committee Chairman, The Queen’s University of Belfast for more information. Note: The first Workshop was held May 24, 1993 at MIOP’93 Sendelfingen Germany, with the technical program organized by the German chapter in co-operation with the UKRI, French and Italian chapters.


Nov. 14: King’s College, London. EDMO’93. The 2nd Workshop on “High Performance Electronic Devices for Microwave and Optoelectronic Devices” (EDMO’93) held in London. EDMO’93 proved to be a highlight of the 1993 activities, combining a successful technical program and organization; 54 delegates attended and the activity was self-financed.

The chapter AdCom activities planned for 1994 currently include fourteen events, consisting of ten evening lecturers and several events of international interest. The chapter lecture series is summarized below:

The chapter is pleased to welcome Lin-da P. B. Katehi, APS AdCom member and Ferdo Ivanek, MTT-S 25th Distinguished Lecturer in its 1994 planning.

The remaining evening lectures for 1994 include:

- Sept. 20: University of Edinburgh; Sept. 22: University College Dublin; and Sept. 28: King’s College, London University, “Progress and Change in Microwave Radio Communications.”
- Oct. 6: Queen’s University, Belfast “Development of the Microwave Mixer: an Industrial Experience” by Terry Oxley.

Early announcement of international events include:

Autumn 1994 (Event to be finalized): Colloquium on Selected European Papers from the 1994 MTT-S International Microwave Symposium and MTT-S/ED-S Microwave & MM Wave Monolithic Symposium, San Diego USA. Note: The aim of the meeting is to provide an opportunity for UKRI (European) engineers who were unable to attend the Symposia in San Diego, CA to hear some of the papers and participate in discussion.

Oct. 24: The Wembley Conference Center, Wembley. The 2nd European Chapter Workshop on “CAE, Modeling and Measurement Verification,” in co-operation with Microwaves 1994 (M’94), the technical program being organized by the UKRI chapter. Please contact Prof. J. A. C. Stewart, Technical Program Committee Chairman, The Queen’s University of Belfast for more information. Note: The first Workshop was held May 24, 1993 at MIOP’93 Sendelfingen Germany, with the technical program organized by the German chapter in co-operation with the UKRI, French and Italian chapters.


Nov. 14: King’s College, London. EDMO’93. The 2nd Workshop on “High Performance Electronic Devices for Microwave and Optoelectronic Applications,” jointly organized by King’s College, London and the UKRI chapter. The chapter welcomes the IEEE EDS co-operative sponsorship of this year’s event. Please contact Dr. Ali A Rezazadeh, Workshop Chairman, King’s College, Strand, London WC2R 2LS for further information. Note: The first Workshop was held on Oct. 18, 1993 at King’s College. The aim is to bring together engineers in the field of compound semiconductor devices applied to microwaves and optoelectronics, to discuss the ever demanding system requirements for advances in semiconductor materials, device processing and circuit design.

Germany Chapter
The elections for the steering committee of the chapter were held by mail. The IEEE Headquarters had given the addresses of 234 EDS members living in Germany. Of these, 10 letters were returned as undeliverable, and from the rest, 112 (50%) responded and cast their votes. The following members were elected to the steering committee (each of them obtained at least 68% of the votes): Dr. M. Berroth, Freiburg Research Institute; Prof. K. Heime, Aachen University; Prof. B. Hoflinger, Stuttgart Research Institute; Dr. W. A. Kellner, Munchen, Prof. D. E. Kohn, Ulm University; and Prof. E. Seegebrecht, Kiel University.

— Terry H. Oxley, Associate Editor

Switzerland CAS/ED Chapter
1993 has been a fruitful year. It started with the election of Prof. Daniel Mlynek, Swiss Federal Institute of Technology, Lausanne as the chairman of the Joint CAS/ED Chapter. Mr. Jacques Kowalczuk of the same institute has been appointed to help as the secretary. Several meetings were held on various technical subjects such as a course on fuzzy logic applications, high-level modelling tools, mixed-mode system simulation and an international seminar on VLSI testing. Meetings were also organized as specialized training courses for professional engineers interested in FPGA and VLSI system design. Some 150 people participated in these courses. It is important to note that these courses were organized in cooperation with the Microswiss Program which is a state program created to promote the use of microelectronics in the Swiss industry. The chapter also participates in the standardization process of the VHDLA language suited for the specification and simulation of analog systems. In addition, it was decided with Prof. Mani Soma, Chairman of the International Working Group for the IEEE 1149.4 Standardization for Mixed Analog/Digital ICs and Boards to use the chapter as a recipient of the work performed in this field.

Some of the remaining activities planned for 1994 are listed below:

- Systems Testing & Reliability, Jul. 6-10, 1994
Region 10

The EDS has a total of eight chapters in Region 10 (Asia Pacific) including: Australian Capital Territory Section, Beijing Section, Hong Kong Section, Indian Council, Korea Council, Malaysia Section, Taipei Section and the very large Tokyo Section. This first issue will introduce only the IEEE EDS Chapters in Beijing, Hong Kong, Taipei, and Tokyo leaving the other Chapters for the next issue.

Beijing EDS Chapter

The Beijing EDS Chapter is relatively new but is growing into an important part of IEEE in China under the leadership of its Interim Chairman, Dr. Han C. Hu. Among the events planned for 1994 is the co-sponsorship of the 3rd International Conference on Millimeter Wave and Far-Infrared Science and Technology in Guangzhou in August 22-26, 1994. This event is sponsored by the Chinese Institute of Electronics, the U.S. Army Research Office and the Georgia Institute of Technology. The Chapter is planning to invite the EDS Distinguished Lecturer, Prof. Dieter K. Schroder, to present a lecture tour in three major cities of Beijing, Nanjing and Xian in 1994 [The confirmed schedule will be published in a future report]. The Chapter is working with IEEE Romania EDS Chapter Chairman, Mr. Adrian Veron, to initiate some joint technical and professional cooperation and hope to see an actual program started in 1994. Later in the year, the Chapter is planning to co-sponsor a technical seminar on HDTV and Display Devices with the Society of Information and Display Chapter in Beijing. For any information on the above events or the Beijing Chapter, please contact Dr. Han C. Hu (Fax: 86-1-4363521).

Hong Kong EDS Chapter

The brand-new Hong Kong EDS Chapter is a direct consequence of the EDS Outreach Program in 1993 when the Section was visited by Lew Terman and Jim Clemens. The Chapter’s inaugural event was a very successful one-day workshop. The Chapter is also actively working with the Hong Kong Section to prepare for the 1995 Region 10 International Conference (TENCON’95) on Microelectronics and VLSI. The conference will be chaired by Prof. Ping Ko, University of California, Berkeley, CA. For further information, please contact Dr. Man Wong (Fax: 852-358-1485 or E-mail: eemwong@uxmail.ust.hk).

Taipei EDS Chapter

With the rapid development of microelectronics manufacturing in Taiwan, the Taipei Chapter has flourished under the distinguished leadership of Dr. C.Y. Lu, who has been recently granted the highest national honor for his contribution in technical leadership and academic excellence. On the industry and technology front, TSMC and UMC, two leading IC foundries in Taiwan, are expected to mass-produce 4Mb SRAM using 4-play 2-metal TFT 0.5 micron CMOS technology. TSMC has broken ground on its 8-in. Fab-II line which is likely to be followed by UMC in 1994. The major activities in 1994 include a two-day Semiconductor Manufacturing Technology Workshop to be held at the Submicron Laboratory, Hsinchu, Apr. 18-19, 1994; and a joint international conference by Japanese MicroProcess Conference and Taiwan Electronic Devices & Material Symposium (EDMS’94) at National Chiao Tung University from Jul. 11 to 15, 1994. For further information, please contact Dr. C.Y. Lu (Fax: 886-35-787954).

Tokyo, Japan EDS Chapter

There is just one large EDS chapter in Japan, the Tokyo Chapter, which was founded in 1971. It is responsible for all IEEE EDS activities.

The Chapter had 988 members as of the end of 1993, but see great potential for that number to expand in the future, especially given that more than one third of all IEDM papers are from Japanese authors. We might then be able to set up one or more regional EDS chapters across the country. At the general meeting of the Chapter held on Dec. 22, 1993 at the University of Tokyo, the new committee members for 1993-94 were elected. They are: Dr. Mukai of Oki Industry Co., Ltd., Chairman; Prof. Hamaguchi of Osaka University, Vice Chairman; Dr. Ueda of Oki Industry Co., Ltd., Secretary; and Prof. Taniguchi, Osaka University, Treasurer.

The major activities of the Chapter in 1992-93 included joint technical meetings with the IEICE [Institute of Electronics, Information, and Communication Engineers] in locations ranging from Okinawa, the southernmost tip of the Japanese Archipelago to Hokkaido in the north. The Chapter holds 12 meetings a year in the areas of “Silicon Devices and Materials” and “Integrated Circuits and Devices.” These meetings are informal and are mostly in Japanese. The Chapter also held one international meeting in Korea on June 24 and 25, 1993. Every year, a meeting is held in December to report on IEDM papers for those who cannot attend the conference.

In 1994-95, the Chapter is planning a similar series of joint technical meetings with the IEICE. The schedule for upcoming meetings is as follows:

Silicon Devices and Materials:


Integrated Circuits and Devices:

Jul. 25, 1994, Tokyo, “Low Voltage, Low Power Consumption and High Speed Technologies for CMOS, BiCMOS, ECL and GaAs LSIs,” Contact Dr. Ichino (Tel: +81-462-40-2257 Fax: +81-462-40-4146).


Sept. 21 - 22, 1994, Nagoya, “ASIC, ASSP-LSIs and Automotive LSIs,” Contact Dr. Usami (Tel: +81-423-23-1111 ext. 3117 Fax: +8423-277764).

If you have any ideas, comments, or proposals regarding the Tokyo Chapter’s activities, please send them to Dr. Ueda, Chapter Secretary (Tel: +81-426-62-6680 Fax: +81-426-67-8367).

— Hiroshi Iwai, Associate Editor
The 1994 SISC will be held at the San Diego Hilton, San Diego, California, December 7-10, 1994, immediately prior to the IEDM. The SISC is sponsored by the Electron Devices Society of IEEE.

The SISC provides a unique forum for device and solid-state physicists and materials scientists to discuss issues of common interest both formally, through invited and contributed talks, and informally during a variety of scheduled activities. Some interests include the various semiconductor interfaces, the physics of insulating thin films, and the interplay between materials science, device physics, and state of the art technology issues. The conference emphasizes Si-based systems, including Si alloys.

DEADLINE FOR SUMMARY SUBMISSION IS AUGUST 15, 1994

The program committee solicits contributed papers for all areas of MOS science and technology including, but not limited to:

- physics of thin dielectrics and their interfaces
- ultracleaning technology and its effect on interface and dielectric properties
- microroughness measurement, modeling, and device-related effects
- metal-, silicide-, and semiconductor-semiconductor interfaces
- radiation and hot-carrier effects
- Si/SiO2 interface defects
- analytical and electrical characterization of semiconductor/dielectric interfaces
- novel oxidation, deposition, and etching techniques

A summary of the work, not to exceed two pages, outlining the major results, accomplishments, and conclusions should be submitted in 22 copies: one copy with the names of the author(s) and institution(s), and 21 copies without the names of the author(s) and institution(s), to be used for paper selection by the committee.

Send all summaries to:

Karen Kuiper
6446 Tucker Ave.
McLean, Virginia 22101, USA

For any further information please contact:

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CALL FOR PAPERS

1994 IEEE International Electron Devices Meeting
December 11-14, 1994
San Francisco Hilton & Towers, San Francisco, CA

Leading Conference in Electron Devices and IC Technology

Papers in the Following Areas are Requested:

- Integrated Circuits
- Quantum Electronics & Compound Semiconductor Devices
- Device Technology
- CMOS Devices and Reliability
- Solid State Devices
- Modeling & Simulation
- Vacuum Electronics
- Detectors, Sensors & Displays

The Abstract Must State:

a. Purpose of work
b. Manner in which it advances the art
c. Specific results and their significance

Abstract Requirements — Deadline is July 1, 1994

- One-page abstract plus up to two pages of figures and tables
- Include title, names, affiliation, address, phone, fax number, technical area
- Accepted abstracts may be used for pre-conference publicity
- Obtain all clearances by deadline
- State if student paper and student travel grant requested
- No facsimiles are accepted for submission
- Send 50 copies of abstracts and figures to:

Melissa Widerkehr
IEDM
1545 18th Street NW, Suite 610
Washington, DC 20036 USA
202/986-1137

Write to this address or call for complete call for papers
CALL FOR PAPERS
IEEE INTERNATIONAL CONFERENCE ON MICROELECTRONIC TEST STRUCTURES
Nara, Japan March 23-25, 1995

The IEEE Electron Devices Society is sponsoring the 1995 International Conference on Microelectronic Test Structures to be held in cooperation with The Institute of Electronics, Information and Communication Engineers, and The Japan Society of Applied Physics. The purpose is to bring together designers and users of test structures to discuss recent developments and future directions. The Conference will be held at the New Public Hall in Nara on March 23-25, 1995. The Conference will be preceded by a one-day Tutorial Short Course on Microelectronic Test Structures on March 22. There will be an equipment exhibition relating to test structure measurements. Original papers presenting new developments in both silicon and gallium arsenide microelectronic test structure research, implementation, and application are solicited. A Best Paper Award will be presented by the Technical Program Committee. Suggested topics include:

Test Structures for Material & Process Characterization
- Carrier Transport Parameters
- Silicon-On-Insulator Material Evaluation
- GaAs Wafer Fabrication
- polysilicon and amorphous Silicon Films

Dimensional & Electrical Integrity of Replicated Features
- MOS Effective Gate Length
- Level-to-Level Registration
- Interconnect System Functionality
- Non-Electrical Techniques

Test Structures for Device & Circuit Modeling
- Modeling Parameter Extraction
- Radiation Hardness Modeling
- Monolithic Microwave Integrated Circuits
- High Frequency Measurement Techniques

Product Failure Analysis from Test Structure Data
- Failure Identification and Mapping
- Machine-Assisted Diagnostics
- Latchup, Soft Error, and Total Dose Effects

Test Structures for Reliability Analysis
- Time-Dependent Dielectric Breakdown
- Wafer-Level Fast Tests
- Electromigration
- Hot-Carrier Injection
- Thermal Monitoring and Analysis

Wafer Fabrication Process Control Test Structures
- Process Uniformity and Worst-Case Analysis
- Wafer Screening and Yield Enhancement
- Experimental Design
- Yield Modeling and Statistical Process Control

Test Structure Measurement Utilization Strategy
- Database Management
- Test Equipment and Programmable Testing
- Expert System and Related Techniques
- Test Structures for Quality Assurance

Paper Submission
Authors are asked to submit for review 36 copies of a 500- to 1000-word summary, a title page, major figures, and data. These should reach the ICMTS95 secretariat by Thursday, August 18, 1994. The title page must include a five-line abstract, the full address and FAX number of the lead author, and author preference for oral or poster session presentation. The selection process will be based on technical merit and will be highly weighted in favor of papers that include measurement data and their analysis. Notices of paper acceptance with instructions for manuscript preparation will be sent to authors of papers selected for presentation by Friday, October 28, 1994. Camera-ready copy will be required from the authors for inclusion in the Conference Proceedings by Monday, January 9, 1995.
The 1995 Symposium will continue emphasizing building-in reliability for VLSI devices and hybrid components during their design, manufacture, and test. Papers are solicited that illustrate the incorporation of reliability physics, reliability engineering, out-of-spec design tolerance, fabrication, assembly, and manufacturing process control to improve system reliability. We encourage papers that address the identification of new microelectronic failure mechanisms, improve insights into existing failure mechanisms, and new or innovative analytical techniques. Papers demonstrating the reliability of advanced packaging techniques/concepts for multichip modules incorporating known good die are also requested.

YOUR PAPERS ARE SOLICITED ON:

• BUILDING-IN RELIABILITY:
  - Integration of reliability engineering with all elements of design
  - Establishing effects of input parameters on product reliability & control
  - Physical basis for design rules & concepts for minimizing jeopardy with experimental validation
  - Particulate control and its effects on reliability
  - Improved manufacturing techniques for wafer fabrication and assembly

• TESTING METHODOLOGIES FOR RELIABILITY, including:
  - In-process wafer fabrication control and assembly, monitors, and sensors
  - Novel test structures and materials
  - Evaluation at wafer level or after full or partial processing
  - Reliability modeling & field failure rate prediction

• ANALYZING FOR RELIABILITY:
  - VLSI failure mechanisms and models applied to:
    - dielectric integrity
    - low power/low voltage issues
    - Optoelectronic failure mechanisms and models applied to:
    - LED/laser degradation
    - passive element degradation
    - Assembly related failure mechanisms and models applied to:
    - bonding
    - package integrity
    - SYSTEM related failure mechanisms, including:
    - automotive
    - Failure analysis techniques: new, advanced, & simplified
    - Analytical instruments & techniques
    - Computer-Aided Reliability (CAR) applications & simulation with experimental validation

SUBMISSION DEADLINE: Received no later than September 23, 1994

Please submit twenty copies of both a one page 50-word abstract, and a two-page summary (including figures) that states clearly and concisely the specific results of your previously unpublished work, why the results are important, and how the results relate to prior work. The twenty copies of the abstract and summary must either be on 8-1/2 by 11-inch or A4 paper and include the title of the paper, and the name, affiliation, complete return address, telephone and telefax numbers, and e-mail address, if available, for each author. Line drawings, key references, and coarse halftones may be included, but please no continuous-tone photographs. Submissions should be by post or express mail rather than by telefax, because telefax is not necessarily legible for review after subsequent duplication. All submissions will be acknowledged. Please allow three weeks. Contact the Technical Program Chair if you have not received acknowledgement for your submission.

Mail to:
Ajit K. Goel, Technical Program Chairman, 1995 IRPS
Onida Research Services, Inc.
540 Waddell Drive, Suite 7
Sunnyvale, CA 94089 USA
Tel. 408-734-2987
Fax 408-734-2984
e-mail: AjitG@AOL.com

PAPER SELECTION: Papers, received by the September 23, 1994 deadline, will be selected based on their technical merits and on their relevance to the Symposium's focus. Paper selection will be performed by groups chosen from industry, government, and university organizations representing a broad spectrum of reliability expertise. Please note that the most common causes for rejection are: incomplete data, prior publication, and insufficient novelty, significance, or relevance to the Symposium.

LATE PAPERS: A limited number of late papers reflecting important last-minute developments will be considered on a space-available basis. Abstract and summary must be received no later than December 1, 1994.

PROCEEDINGS MANUSCRIPT: Final, camera-ready manuscripts must be received by February 2, 1995 so that the Proceedings can be available at the Symposium.

CO-SPONSORS: The Reliability and the Electron Devices Societies of The Institute of Electrical and Electronics Engineers, Inc. are the co-sponsors of the Symposium.

For general conference information, contact:
Joe McPherson, General Chairman, 1995 IRPS
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P.O. Box 655012 M/S 385
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Tel. (214) 995-2183
Fax (214) 995-2932
e-mail: JOMC%mimi@magic.itg.TI.com
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Tel: (408) 943-4861  
Fax: (408) 943-2118 |
## Electron Devices Society Chapters and Representatives

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<th>Representative(s)</th>
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<tbody>
<tr>
<td>Central New England</td>
<td>T.B. Ramachandran</td>
<td>(508) 692-7800</td>
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<tr>
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<td>Stephen Wanuga</td>
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<tr>
<td>Cleveland</td>
<td>Jose L. Christian, Jr.</td>
<td>(216) 433-5519</td>
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<td>Columbus</td>
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<td>(614) 292-2572</td>
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<td>(215) 519-4263</td>
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**REGION 3 (Southeastern USA)**

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<tr>
<td>Orlando</td>
<td>Kalpathy B. Sundaram</td>
<td>(407) 823-5326</td>
</tr>
<tr>
<td>Virginia Mountain</td>
<td>Inder J. Bahl</td>
<td>(703) 563-8638</td>
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**REGION 4 (Central USA)**

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<tr>
<td>Chicago</td>
<td>Carl R. Kannewurf</td>
<td>(708) 491-8163</td>
</tr>
<tr>
<td>Milwaukee</td>
<td>James Richle</td>
<td>(414) 288-5326</td>
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<tr>
<td>Southeastern Michigan</td>
<td>Joseph W. Burns</td>
<td>(313) 994-1200</td>
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<tr>
<td>Twin Cities</td>
<td>Jay L. Farnam</td>
<td>(512) 932-1500</td>
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**REGION 5 (Southwestern USA)**

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<td>Central Texas</td>
<td>John K. Lowell</td>
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<td>Dallas</td>
<td>Charles B. Yarling</td>
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<td>(214) 768-3324</td>
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<td>Pikes Peak</td>
<td>Jeffrey T. Williams</td>
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<td>Saint Louis</td>
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<td></td>
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**REGION 6 (Western USA)**

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<tr>
<td>Los Angeles</td>
<td>Paramjit Singh</td>
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<td>Oregon</td>
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<tr>
<td>Kitchener-Waterloo</td>
<td>Aroki Nathan</td>
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<td>Montreal</td>
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<td>(519) 885-1211</td>
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<tr>
<td>Ottawa</td>
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<td>(514) 424-3340</td>
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<td>Toronto</td>
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<tr>
<td>Germany</td>
<td>Klaus Heime</td>
<td>49-241-807745</td>
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<td>Hungary</td>
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<td>36-1-181-2908</td>
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<td>Israel</td>
<td>Asher Madjar</td>
<td>972-4-796-128</td>
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<td>Switzerland</td>
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<td></td>
<td>Terry H. Oxley</td>
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**REGION 9 (Latin America)**

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<tr>
<td>Rio De Janeiro</td>
<td>Jose R. Bergmann</td>
<td>55-21-529-9254</td>
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**REGION 10 (Asia and Pacific)**

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<tbody>
<tr>
<td>Australia</td>
<td>Chennupati Jagadish</td>
<td>61-6-249-0363</td>
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<td>Beijing</td>
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<td>Hong Kong</td>
<td>Man Wong</td>
<td>852-339-7257</td>
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<tr>
<td>India</td>
<td>Shihan K. Koul</td>
<td>91-11-663-074</td>
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<td>Korea</td>
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<td>Malaysia</td>
<td>Burhanuddin Y. Majlis</td>
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<tr>
<td>Tokyo</td>
<td>C.Y. Lu</td>
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<td>Tokyo</td>
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